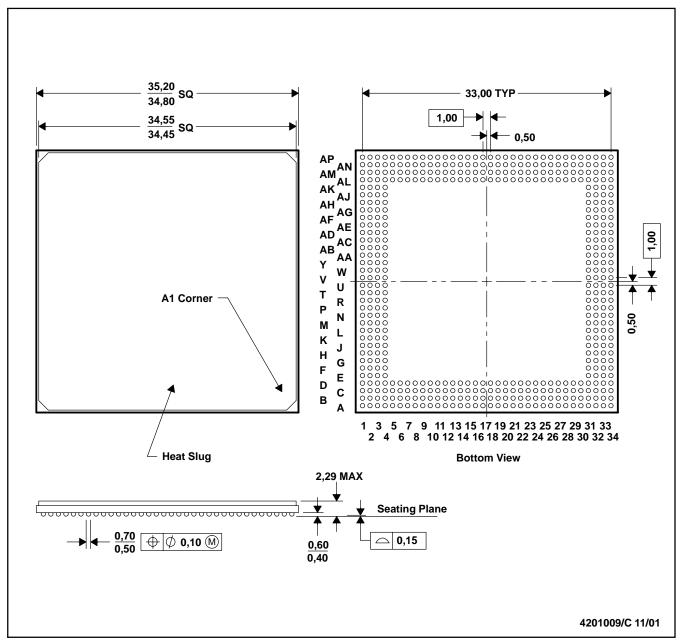
GNH (S-PBGA-N480)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Thermally enhanced plastic package with a heat slug (HSL)

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